ASSOCIATION CONNECTING	Material Composition © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara the declaration	tion of the s encompasse	ubstances es all lowe	within the manufactu r level materials for v	vhich the	item. Note: i manufacture	f the item is an as r has engineering	ssembly with lower responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Inform	ation														
Company name*			Company unique ID				Unique ID Authority				Respor	Response Date*			
onsemi											2023-0	2023-06-08			
Contact Name			Title - Contact				Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Requeste	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Dat	e Version Manufacturing Site			Weight*	UOM	Unit Type		
		NCP81143MNTXG Vi		Vr Controller			2023-06-08		I	PH1		92.28	mg	Each	
Manufacturing]	Proccess Information	n													
Terminal Plating / Grid Array Material Terminal			erminal Base Alloy J-STD-020 MSL		L Rating	Peak Process Body Temperatu		ure Max Time at Peak Temper		mperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU A			U Alloy	1			260 C 30			seconds 3					
Comments															
level 1 - maximum ti	ime at peak temperature o	during sol	dering is 10-3	0 seconds											
For more information	on regarding material con	1position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	8 RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	4.09	mg	Supplier	Silicon (Si)	7440-21-3		4.09	mg	
Die Attach	0.4	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.052	mg	
			Supplier	Silver (Ag)	7440-22-4		0.348	mg	
Lead Frame	36.75	mg	Supplier	Silver (Ag)	7440-22-4		0.735	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.0367	mg	
			Supplier	Iron (Fe)	7439-89-6		0.8085	mg	
			Supplier	Copper (Cu)	7440-50-8		35.1698	mg	
Mold Compound-Black	47.47	mg		Epoxy Phenol Resin	proprietary data		4.2723	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		43.1977	mg	
Plating	3.01	mg	Supplier	Tin (Sn)	7440-31-5		3.01	mg	
Wire Bond - Cu	0.56	mg	Supplier	Copper (Cu)	7440-50-8		0.56	mg	